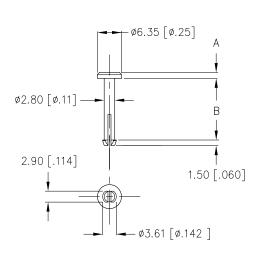
## ALPHA

# PIP 3.175



THE PIP3.175 SERIES MOUNTS THE HEATSINK TO THE PCB USING A SPRING, OBTAINING ADEQUATE PRESSURE REQUIRED FOR THERMAL INTERFACE MATERIAL PERFORMANCE IS EASILY ATTAINED BY CHOOSING AN APPROPRIATE SPRING (NOT INCLUDED.).





P/N	PART NAME	А	В
S001YZ3M	PIP3.175x7.0 [TH]	0.89 [.035]	7.00 [.276]
S001YZ1H	PIP3.175x8.5 [TH]		8.50 [.335]
S001YZ10	PIP3.175x9.8 [TH]	1.27 [.050]	9.80 [.386]
S001YZ0T	PIP3.175x11 [TH]		11.00 [.433]
S001YZ0N	PIP3.175x11.5	1.55 [.061]	11.50 [.453]
S001YZ1P	PIP3.175x13.2		13.20 [.520]
S001YZ0M	PIP3.175x14.3		14.30 [.563]
S001YZ0Y	PIP3.175x18.8		18.80 [.740]
S001YZ0X	PIP3.175x20.3		20.30 [.799]



: BRASS (ROHS COMPLIANT)

C6801 SAN-ETU METALS BZ5

OR EQUIVALENT

• DIMENSIONS mm [inch]



#### HEATSINK:

REQUIRES HEATSINK HOLE DIAMETER OF 3.45 [.136] IF "PIP3.175 + SPRING" NEEDS TO BE CAPTIVE. (WHEN BASE THICKNESS IS LESS THAN 2 mm OR SPRING IS PRE-COMPRESSED, HEATSINK HOLE DIAMETER 3.30 IS RECOMMENDED.)

#### BOARD

PUSH-ROD

LOWER-BASE

REQUIRES  $\emptyset 3.175 \pm 0.05$  [ $\emptyset .125 \pm .002$ ] THRU HOLES IN BOARD. USE OF PLATED HOLES TO REDUCE EXCESSIVE WEAR AND INSERTION FORCE IS RECOMMENDED.

### • INSTALLATION:

THE SPRING SHOULD NOT BE COMPRESSED TO SOLID LENGTH DURING INSTALLATION AND SHOULD BE SUPPORTED BY THE LOWER-BASE. PUSH-ROD AND LOWER-BASE NEEDS TO BE OBTAINED/PRODUCED LOCALLY.

MAY 2015

Alpha Company Ltd.

PCB

HEATSINK

256-1 UEDA, NUMAZU-CITY SHIZUOKA-PREF., JAPAN

- INTERFACE MATERIAL

PHONE +81(55)966 0789 FAX +81(55)966 9192 E mail : alpha@micforg.co.jp URL : http://www.micforg.co.jp

CHIP

- PCB THRU HOLE

Alpha Novatech, Inc. - a subsidiary of Alpha Company.

473 Sapena Ct. #12  $\,$  Santa Clara, CA 95054  $\,$  USA

PHONE +1(408)567-8082

FAX +1(408)567-8053

E mail: sales@alphanovatech.com

URL: http://www.alphanovatech.com